Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info: ti.com/support
Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
Created on: **06/03/2022**

Details for "LP5996SD-3033/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
LP5996SD-3033/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	DSC | 10	3 x 3 x 0.7	19.2

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000675	7	0.000005	0
Precious Metals	Gold	7440-57-5	0.148142	99.997975	999980	0.770245	7702
Precious Metals	Silver	7440-22-4	0.000002	0.00135	14	0.00001	0
Sub-Total			**0.148145**	**100**	**1000000**	**0.77026**	**7703**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.367499	74.999949	749999	1.910762	19108
Thermoplastics	Epoxy	85954-11-6	0.1225	25.000051	250001	0.636922	6369
Sub-Total			**0.489999**	**100**	**1000000**	**2.547684**	**25477**
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	8.780605	97.67079	976708	45.653582	456536
Copper and Its Alloys	Iron	7439-89-6	0.192836	2.145005	21450	1.002625	10026
Copper and Its Alloys	Phosphorus	7723-14-0	0.002715	0.0302	302	0.014116	141
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000189	0.002102	21	0.000983	10
Zinc and Its Alloys	Zinc	7440-66-6	0.013656	0.151902	1519	0.071003	710
Sub-Total			**8.990001**	**100**	**1000000**	**46.742308**	**467423**
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.522	100	1000000	2.714069	27141
Sub-Total			**0.522**	**100**	**1000000**	**2.714069**	**27141**
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	7.105186	90.500003	905000	36.942465	369425
Thermoplastics	Epoxy	85954-11-6	0.745848	9.499997	95000	3.877937	38779
Sub-Total			**7.851034**	**100**	**1000000**	**40.820402**	**408204**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.231934	100	1000000	6.405276	64053
Sub-Total			**1.231934**	**100**	**1000000**	**6.405276**	**64053**
Total			19.233113			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
Created on: 06/03/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.